

INFORMATION DISCLOSURE CITATION
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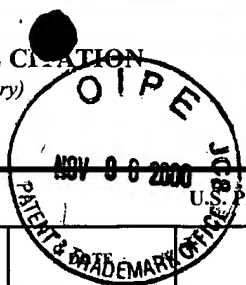
Docket Number (Optional)
11675.76.1.1

Application Number
09/627,381

Applicant(s)
Sandhu, et al.

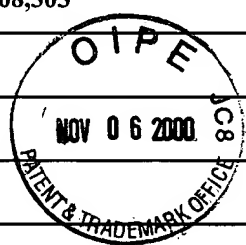
Filing Date
July 28, 2000

Group Art Unit
627381
Not yet assigned



U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Ty	A	5,445,996	8/95	Kodera et al.	438	633	
Ty	B	5,486,493	1/96	Jeng	438	623	
Ty	C	5,399,235	3/95	Mutsaers et al.	438	633	
Ty	D	5,420,075	5/95	Homma et al.	438	624	
Ty	E	5,599,740	2/97	Jang et al.	438	626	
Ty	F	5,677,239	10/97	Isobe	438	633	
Ty	G	5,795,829	8/98	Shen	438	694	
Ty	H	5,708,303	1/98	Jeng	257	758	



FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Ty	1	M.K. Jain et al., "Advanced Metalization and Interconnect Systems for ULSI Applications: Homogenous and Multilayer Low-K Interlevel Dielectric Architectures for Capacitance Reduction," Conference at University of California, Berkeley, California, October 1996.
Ty	2	Tetsuya Homma, "Fluorinated SiO2 Films for Interlayer Dielectrics in Quarter-Micron ULSI Multilevel Interconnections," Mat. Res. Soc. Symp. Proc., Vol. 381, pp. 239-248, 1995.

EXAMINER
Guach

DATE CONSIDERED
10/11/01

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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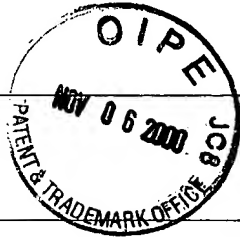
*EXAMINER

INITIAL

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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J. Wary et al., "Vacuum-Deposited Parylene AF-4: A Thermally Stable, Low Dielectric Constant Polymer For Interlayer Dielectric Use," DUMIC Conference, pp. 207-213, February, 1996.



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